

## Technical datasheet

# KEKO silver Via Fill paste –AgV-1

KEKO AgV-1 paste is a standard co-firable silver Via Fill paste specially design for use with KEKO LTCC SK-47 tape suited to provide reliable interconnections between silver conductor layers and lines. It offers several benefits such as low cost highly conductive metallization, high circuit density and co-fireable process.

### Typical processing procedure for KEKO AgV-1 paste

For detail information about use of the KEKO AgV-1 paste on KEKO SK-47 LTCC tape please see the LTCC PROCESSING INSTRUCTIONS for KEKO SK-47 LTCC Tape.

### Design

For detailed recommendations about the design of circuit please contact KEKO Equipment stuff and see the LTCC PROCESSING INSTRUCTIONS for KEKO SK-47 LTCC Tape.

### Screen printing

The paste should be thoroughly mixed before use. Mix the paste slowly and gently by hand with a dust free spatula (plastic or stainless steel) for 1 minute for best results. Avoid air entrapment.

Printing should be performed in a clean and well-ventilated area. For the best results, the use of the KEKO Equipment screen printing machines from series P and stencils provided by KEKO are recommended. Optimum printing characteristics are generally achieved at a room temperature of 20-25 °C.

Vias in KEKO SK-47 LTCC tape are usually filled using metal stencils and screen printing technique.

### Thinning

The paste composition is adjusted for optimal performance, therefor thinning of the paste is

not recommended. Improper thinning may affect filling characteristics. Solvent evaporation during normal use of the paste may be replenish but care should be taken to not over-thin.

### Drying

It is recommended to dry sheets in KEKO dryer series SD. Any other conventional drying ovens at a maximum temperature of 70 °C for 10 to 20 minutes may be used. Do not over-dry.

### Lamination and Firing

The details about lamination and firing are described in LTCC PROCESSING INSTRUCTIONS for KEKO SK-47 LTCC Tape.

### Storage and Shelf Life

Store the pastes in tight sealed containers at room temperature in dry place. Avoid direct sunlight or other source of heat radiation. The shelf life of unopened package is 6 months.

Settling of solids may occur, therefore the paste should be thoroughly mixed prior to use.

### Safety and Handling

For Safety and Handling information pertaining to this product, read the Material Safety Data Sheet (MSDS).

### Typical properties of KEKO AgV-1 paste

Viscosity @ 25°C Brookfield HBDV-II, SC4-14 spindle,1 rpm)	500-1500 Pa·s
Clean-Up Solvent	Isopropanol
Thinner	KEKO Thinner 07
Solid content	92 %
Via Diameter Resolution (µm)	100
Fired Resistivity (mΩ/sq <sup>2</sup> )	<2

**This data represents typical properties measured by on our own test specimens and it is not intended to be used as specification limits.**